

ABSTRACT OF THE DISCLOSURE

POLISHING APPARATUS AND POLISHING METHOD

5 A polishing apparatus capable of monitoring an accurate progress of polishing is disclosed. The polishing apparatus includes: a polishing table for supporting a polishing pad; a table motor configured to rotate the polishing table; a top ring configured to press a substrate against the polishing pad to polish the substrate; a dresser configured to dress the polishing pad while oscillating on the polishing pad during polishing of the substrate;
10 a filtering device configured to remove a vibration component, having a frequency corresponding to an oscillation period of the dresser, from an output current signal of the table motor; and a polishing monitoring device configured to monitor a progress of polishing of the substrate based on the output current signal from which the vibration component has been removed.

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FIG. 1